



## Advance Product Change Notification

201407012A

**Issue Date:** 16-Sep-2014

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



# QUALITY

### Change Category

- |  |  |  |  |
|--|--|--|--|
| <input type="checkbox"/> Wafer Fab process   | <input type="checkbox"/> Assembly Process              | <input type="checkbox"/> Product Marking                           | <input type="checkbox"/> Design                    |
| <input type="checkbox"/> Wafer Fab materials | <input checked="" type="checkbox"/> Assembly Materials | <input checked="" type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification  |
| <input type="checkbox"/> Wafer Fab location  | <input type="checkbox"/> Assembly Location             | <input type="checkbox"/> Test Location                             | <input type="checkbox"/> Packing/Shipping/Labeling |

**Change of bond wire and release of 2nd source mold compound in DFN2020-3 (SOT1061)**

### Details of this Planned Change

Scheduled changes affect low VCEsat ("BISS") transistors in DFN2020-3 (SOT1061) package only.

- (1) The bond wire material will be changed from gold to copper. Gold wire remains qualified for supply security reasons only.
- (2) A second source mold compound supplier will be introduced.
- (3) In the datasheet of PBSS4330PA and PBSS5330PA, the measurement condition of ICES will be changed from VCE=30V to VCE=24V.

Old product: Wire material is gold (Au), (with currently used mold compound suppliers)

Changed product: Wire material is copper (Cu) or gold (Au) (with currently used first and new second source mold compound supplier)

The design and materials of all other components will remain unchanged: die, die attach, and lead frame.

Reliability qualification and full electrical characterization over temperature will be performed. For details please see the Self Qualification Plan.

No change on thermal behavior or mechanical dimensions. Electrical parameters (apart from the mentioned change of the ICES measurement condition) will remain unchanged (in specification and with the same distribution).

### Why do we Plan this Change

- (1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.
- (2) Following NXP company policy of second source material availability, a second source mold compound will be added to the BOM for associated types in DFN2020MD-6 (SOT1220) package. The second source supplier is already well established for NXP semiconductor products.
- (3) The measurement condition is adapted to the standard condition used for NXP BISS transistors.

#### **Identification of Affected Products**

Changed products can be identified by date code after implementation.

### **Product Availability**

#### **Sample Information**

Samples are available upon request

Samples can be ordered now and will be shipped after FPCN issue date.

#### **Production**

Planned first shipment 01-Feb-2015

### **Impact**

No impact to the products' functionality anticipated.

#### **Data Sheet Revision**

A new datasheet will be issued

#### **Disposition of Old Products**

Existing inventory will be shipped until depleted

### **Timing and Logistics**

The Self Qualification Report will be ready on 20-Oct-2014.

The Final PCN is planned to be issued on: 20-Oct-2014.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 16-Oct-2014.

### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** GA Customer Support

**e-mail address** DiscrQA.Helpdesk.GA-Products@nxp.com

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NXP Quality Management Team.

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